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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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FC6546010R

Dual N-channel MOS FET

For switching

■ Features

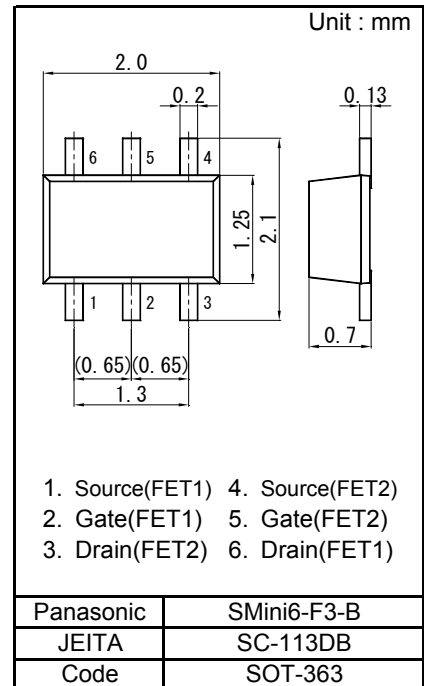
- Low drive voltage: 2.5 V drive
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol V6

■ Basic Part Number : Dual FK350601 (Individual)

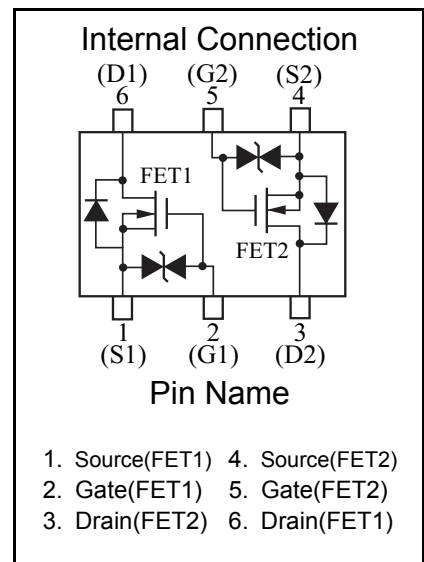
■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter		Symbol	Rating	Unit
FET1	Drain-source breakdown voltage	VDSS	60	V
	Gate-source breakdown voltage	VGSS	±12	V
FET2	Drain current	ID	100	mA
	Pulse drain current	IDp	200	mA
Overall	Total power dissipation	PT	150	mW
	Channel temperature	Tch	150	°C
	Operating ambient temperature	Topr	-40 to + 85	°C
	Storage temperature	Tstg	-55 to +150	°C



■ Electrical Characteristics Ta = 25 °C ± 3 °C

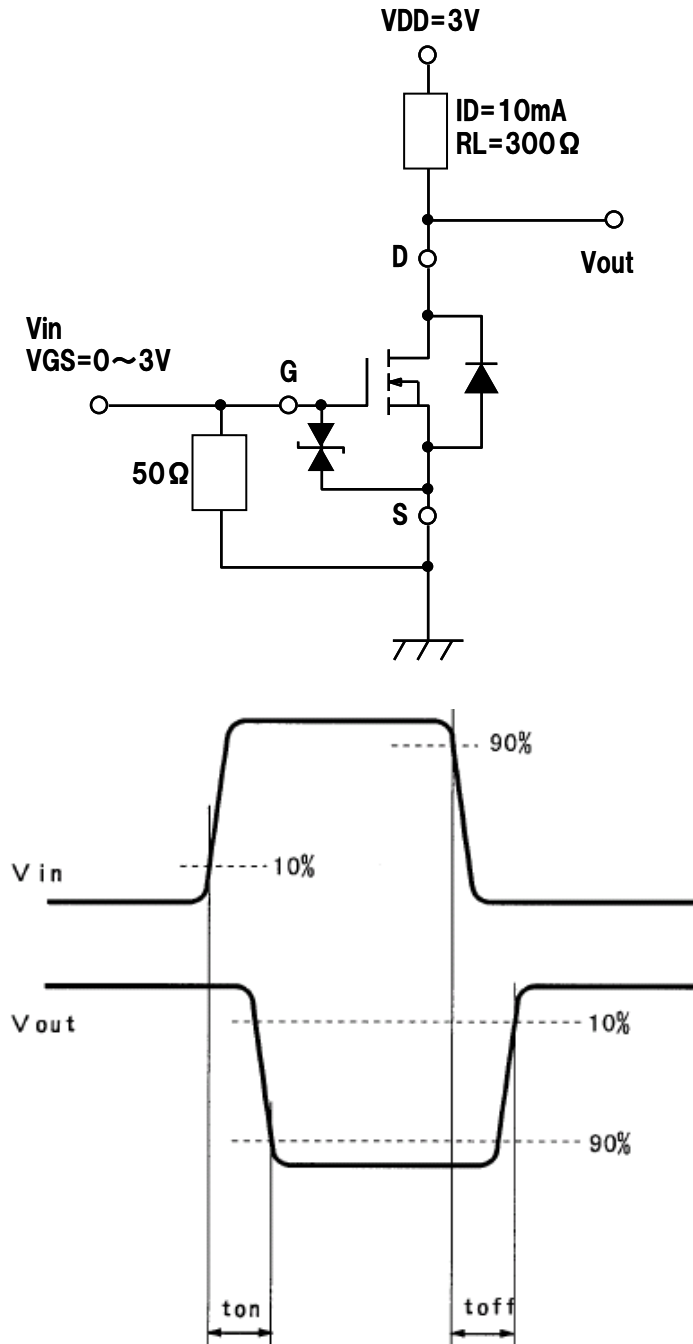
FET1,FET2

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source breakdown voltage	VDSS	ID = 1 mA, VGS = 0	60			V
Drain-source cutoff current	IDSS	VDS = 60 V, VGS = 0			1.0	μA
Gate-source cutoff current	IGSS	VGS = ±10 V, VDS = 0			±10	μA
Gate threshold voltage	VTH	ID = 1.0 μA, VDS = 3.0 V	0.9	1.2	1.5	V
Drain-source ON resistance	RDS(on)1	ID = 10 mA, VGS = 2.5 V		8	15	Ω
	RDS(on)2	ID = 10 mA, VGS = 4.0 V		6	12	Ω
Forward transfer admittance	Yfs	ID = 10 mA, VDS = 3.0 V	20	60		mS
Input capacitance	Ciss	VDS = 3 V, VGS = 0, f = 1 MHz		12		pF
Output capacitance	Coss			7		pF
Reverse transfer capacitance	Crss			3		pF
Turn-on time *1	ton	VDD = 3 V, VGS = 0 to 3 V ID = 10 mA		100		ns
Turn-off time *1	toff	VDD = 3 V, VGS = 3 to 0 V ID = 10 mA		100		ns

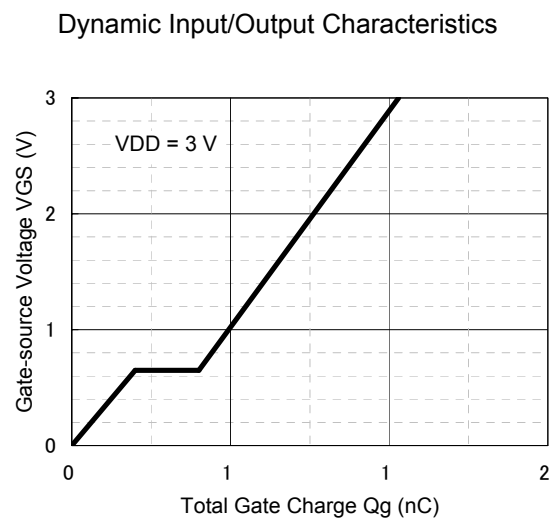
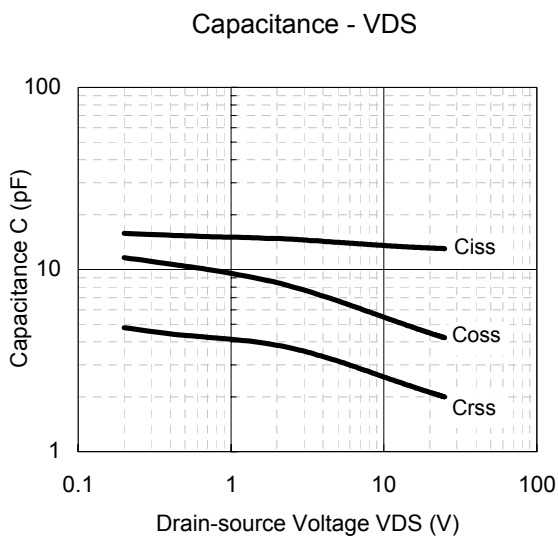
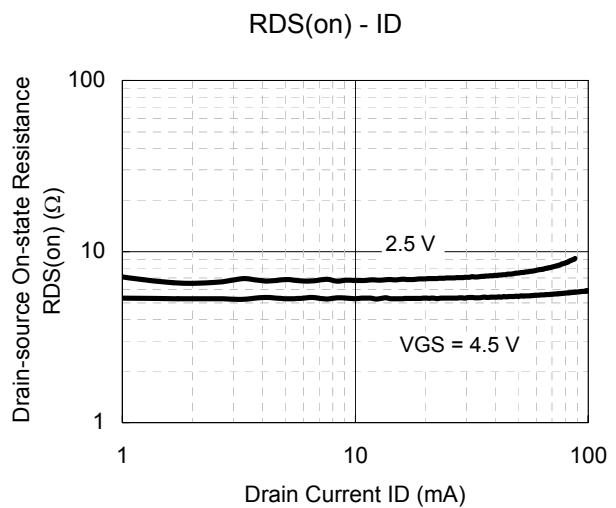
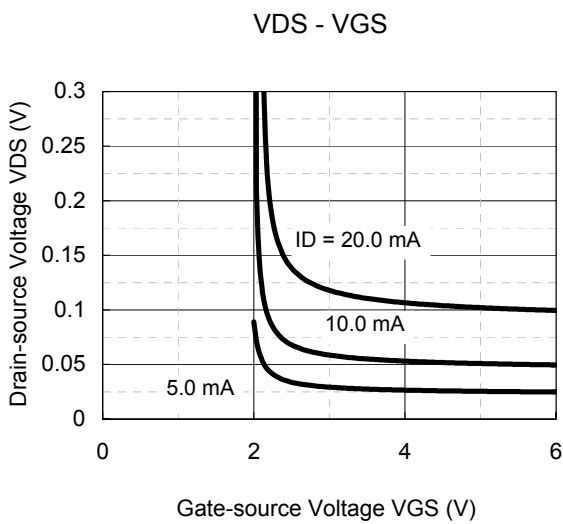
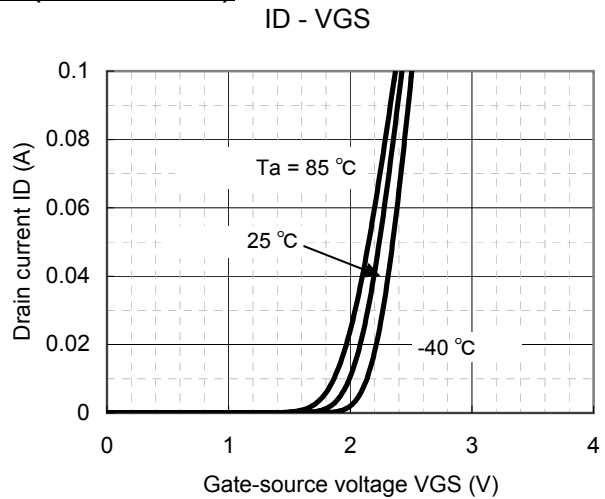
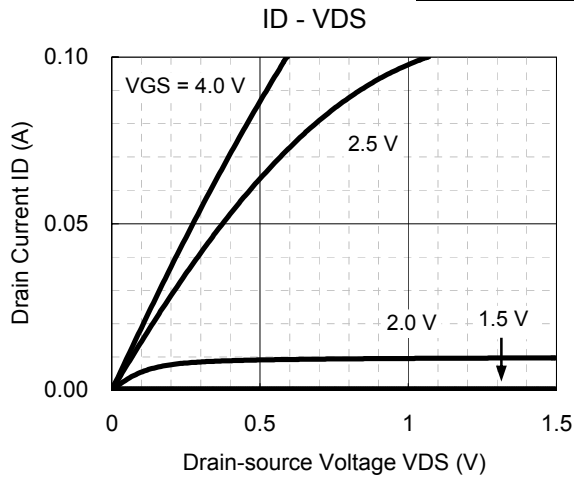
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Turn-on and Turn-off test circuit

*1 Turn-on, Turn-off measurement circuit

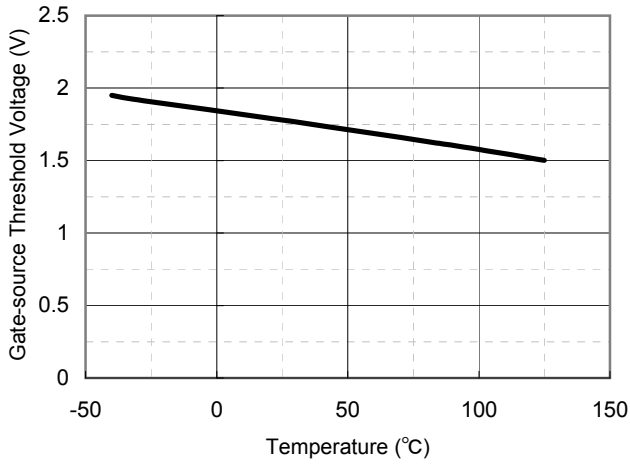


Technical Data (reference)

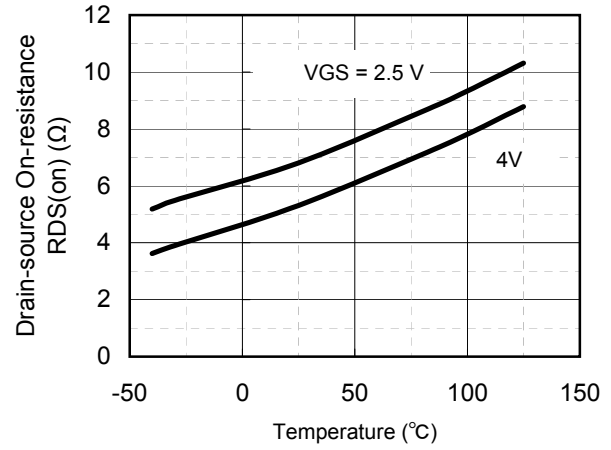


Technical Data (reference)

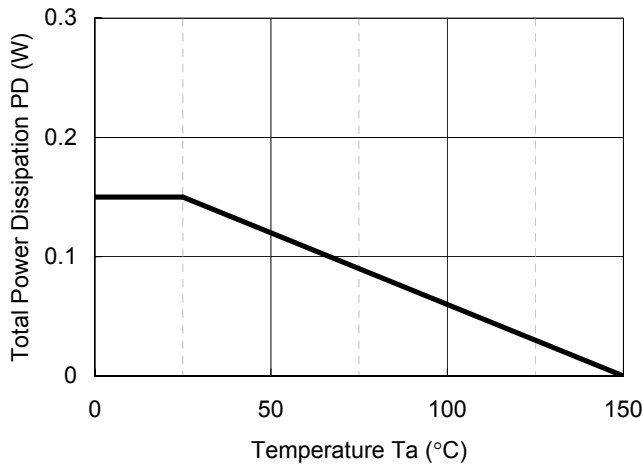
V_{th} - T_a



R_{DS(on)} - T_a

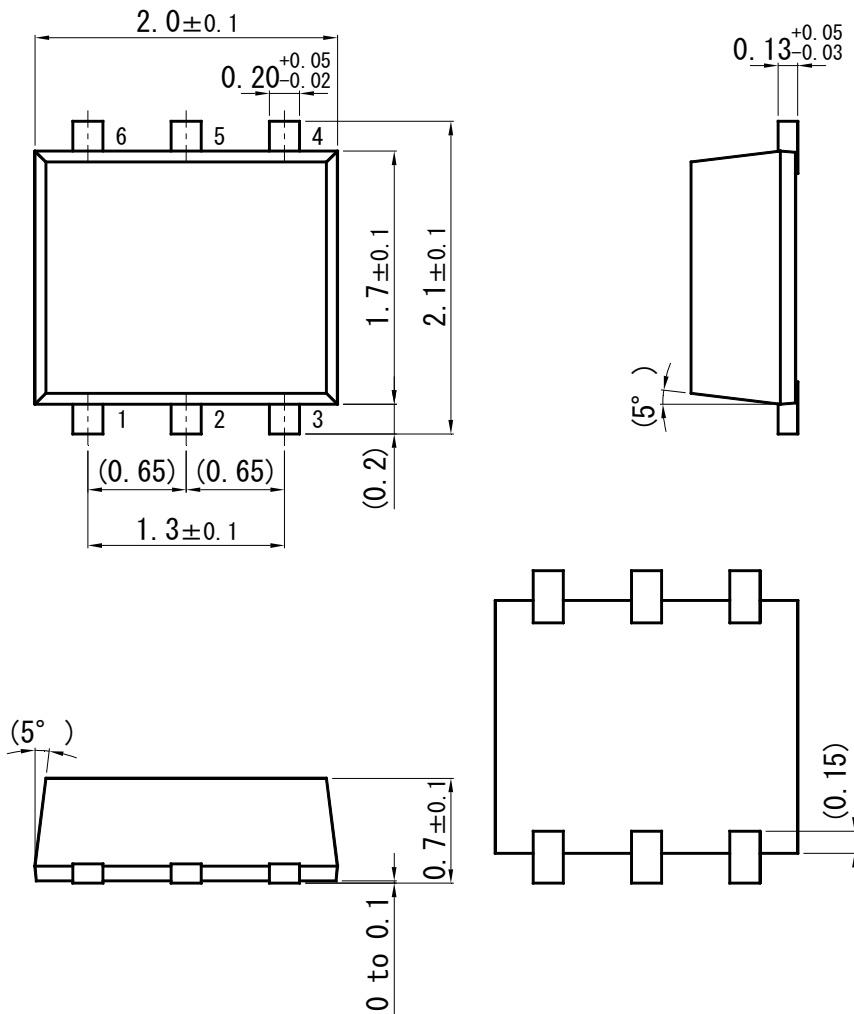


PD - T_a

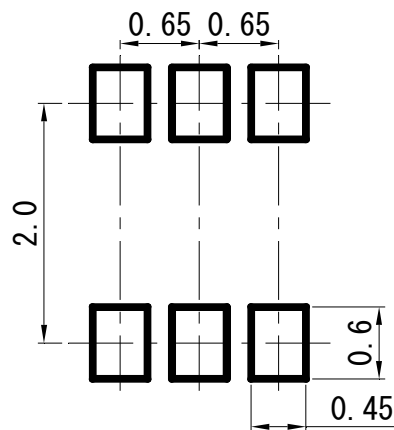


SMini6-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit : mm)



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